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U.S. PATENT AND TRADEMARK OFFICE

07-11-2005					
Case Docket No. ABE-026 RCE ice					
RECORDATION FORM CO PATENTS ONL 103036906					
To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.					
1. Name of conveying parties:					
Shigeru UMENO, Masataka HOURAI, Masakazu SANO and Shinichiro MIKI					
Additional name(s) of conveying party(ies) attached? Yes No XX_					
2. Name and address of receiving party:					
Name: Sumitomo Mitsubishi Silicon Corporation					
Internal Address:					
Street Address: 2-1, Shibaura 1-chome, Minato-ku, Tokyo 105-8634, Japan					
Additional name(s) & address(es) attached? Yes No _XX					
3. Nature of conveyance:					
XX Assignment Merger					
Security Agreement Change of Name					
Other:					
Execution Date: October 8, 2004					
4. Title:  MANUFACTURING METHOD OF SILICON WAFER					
5. Application number(s) or patent number(s):					
If this document is being filed together with a new application, the execution date of the application is: October 8, 2004					
A. Patent Application No.(s) B. Patent No.(s)					
Additional numbers attached? Yes No XX_					

PATENT REEL: 016749 FRAME: 0512

Case Docket No. ABE-026  U.S. DEPARTMENT OF COMMERCE				
Patent and Trademark Office RECORDATION FORM COVER SHEET				
PATENTS ONLY				
6. Name and address of party to whom correspondence concerning document should be mailed:				
Name: KUBOVCIK & KUBOVCIK The Farragut Building Suite 710 900 17th Street, N.W. Washington, D.C. 20006				
7. Total number of applications and patents involved:				
8. Total fee (37 CFR 3.41)				
XX Authorized to be charged by credit card				
Authorized to be charged to Deposit Account				
9. Deposit Account No.: <u>111833</u>				
10. In the event any additional fees are required, please charge our Deposit Account No.: <u>111833</u> .				
11. Statement and signature.				
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.				
Keiko Tanaka KubovcikJuttoFebruary 16, 2005Name of Person SigningSignatureDate				
Total number of pages, including cover sheet, attachments, and document:				
Atty. Docket No. ABE-026				
KTK/jbf				

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PATENT REEL: 016749 FRAME: 0513

**RECORDED: 02/16/2005** 

## **U.S. ASSIGNMENT**

	IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter ASSIGNOR) by			
Insert ASSIGNEE'S Iame(s) Address(es))	Sumitomo Mitsubishi Silicon Corporation 2-1, Shibaura 1-chome, Minato-ku, Tokyo 105-8634, Japan			
	(hereinafter ASSIGNEE), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled			
Title of Invention)	Manufacturing method of silicon wafer			
FIf the assignment is eing filed after the ling of the pplication, this section oust be completed)	for which application for Letters Patent of the United States was executed on even date herewith unless otherwise indicated below:			
	*filed on, Serial No  (Kubovcik & Kubovcik is hereby authorized to insert the series code, serial number and/or filing date, when known)			
	and to all Letters Patent of the United States to be obtained thereof on said application or any continuation, divisional, substitute, reissue or reexamination thereof for the full term or terms for which the same may be granted.			
	The ASSIGNOR agrees to execute all papers necessary in connection with this application and any continuing, divisional, reissue or reexamination applications thereof and also to execute separate assignments in connection with such applications as the ASSIGNEE may deem necessary or expedient.			
	The ASSIGNOR agrees to execute all papers necessary in connection with any interference, litigation, or other legal proceeding which may be declared concerning this application or any continuation, divisional, reissue or reexamination thereof or Letters Patent or reissue patent issued thereon and to cooperate with the ASSIGNEE in every way possible in obtaining and producing evidence and proceeding with such interference, litigation, or other legal proceeding.			
gnatures)	IN WITNESS WHEREOF, t signature(s).	he undersigned inventor(s) has	(have) affixed his/her/their	
	Shigery Umeno (SIGNATURE)	Shigeru Umeno (TYPE NAME)	Oct. 8, 2004.	
	Masatata/Joulou (SIGNATURE)  Masakagn Sano (SIGNATURE)  Shin Milei	Masataka Hourai (TYPE NAME)	Oct. 8. 2004.	
	Hasakayn Sano (SIGNATURE)	Masakazu Sano (TYPE NAME)	Oct, 8, 200 x	
	Shin Milei	Shinichiro Miki	Oct. 8. 2004 (DATE)	
	(SIGNATURE)	(TYPE NAME)	(DATE)	
	(SIGNATURE)	(TYPE NAME)	(DATE)	
	NO LEGALIZATION REQUIR	SEL)	08/00	

PATENT REEL: 016749 FRAME: 0514